

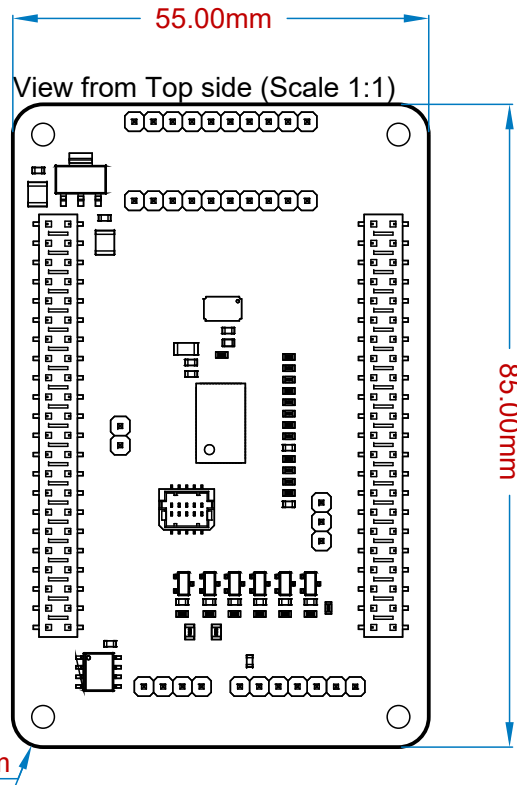
Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
Surface Material	Top Solder	0.010mm(0.400mil)	Solder Resist	Solder Mask	GTS
Copper	Top	0.035mm(1.378mil)		Signal	GTL
Core		0.127mm(5.000mil)	FR-4	Dielectric	
Copper	GND1	0.035mm(1.378mil)		Internal Plane	GP1
Prepreg		0.127mm(5.000mil)		Dielectric	
Copper	MID	0.035mm(1.378mil)		Signal	G1
Core		0.850mm(33.465mil)		Dielectric	
Copper	VM	0.035mm(1.378mil)		Signal	G2
Prepreg		0.127mm(5.000mil)		Dielectric	
Copper	GND2	0.035mm(1.378mil)		Internal Plane	GP2
Core		0.127mm(5.000mil)		Dielectric	
Copper	Bottom	0.035mm(1.378mil)		Signal	GBL
Surface Material	Bottom Solder	0.010mm(0.400mil)	Solder Resist	Solder Mask	GBS
	Bottom Overlay			Legend	GBO

Total thickness: 1.588mm(62.533mil)

Notes:

1. MATERIAL : FR-4-2 NATURAL EPOXY/FIBERGLASS
2. APPLY SOLDERMASK ON BOTH SIDES
COLOR: WHITE
FABRICATOR SHALL MAKE NECESSARY MODIFICATIONS TO SOLDERMASK PHOTOPLOT FILES FOR OPTIMAL SOLDERMASK COVERAGE BETWEEN FINE PITCH COMPONENT LEADS.
3. FINISH ALL EXPOSED COPPER SURFACES WITH IMMERSION GOLD.
4. HOLE SIZES APPLY AFTER PLATING.
5. APPLY SILKSCREEN TO BOTH SIDES
COLOR: BLACK
FABRICATOR SHALL MAKE NECESSARY MODIFICATIONS TO LEGEND PHOTOPLOT FILES TO ENSURE NO LEGEND INK COVERS ANY COMPONENT PAD OR VIA PAD.
6. MODIFIED PHOTOPLOT FILES ARE TO BE RETURNED BEFORE ORDER DELIVERED.
7. ALL PRINTED CIRCUITBOARD NETS SHALL BE ELECTRICALLY TESTED FOR OPENS AND SHORTS.
8. FABRICATION OF PCB TO COMPLY WITH IPC-A-600 CLASS II . CURRENT REVISION.



Title: TMC4671-EVAL

Version: 1.2

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